Analog Devices Welcomes Hittite Microwave Corporation

NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED
**LP4 (E) Package**

**BOTTOM VIEW**

**NOTES:**
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. PAD SPACING TOLERANCE IS NON-CUMULATIVE
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
   PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

**Package Information**

<table>
<thead>
<tr>
<th>Part Number Suffix</th>
<th>Package Body Material</th>
<th>Lead Finish</th>
<th>MSL Rating</th>
<th>Package Marking[^3][^4]</th>
</tr>
</thead>
<tbody>
<tr>
<td>LP4</td>
<td>RoHS Compliant Mold Compound</td>
<td>Sn/Pb Solder</td>
<td>MSL1 [^1]</td>
<td>HNNN XXXX</td>
</tr>
<tr>
<td>LP4E</td>
<td>RoHS Compliant Mold Compound</td>
<td>100% matte Sn</td>
<td>MSL1 [^2]</td>
<td>HNNN XXXX</td>
</tr>
</tbody>
</table>

[^1]: Max peak reflow temperature of 235 °C
[^2]: Max peak reflow temperature of 260 °C
[^3]: 4-Digit lot number XXXX
[^4]: 3-Digit part number NNN
Suggested LP4 (E) PCB Land Pattern

NOTES:
1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.
3. SOLDERMASK ON FAR SIDE SHOULD TENT OR PLUG VIA HOLES.
For price, delivery, and to place orders, please contact Hittite Microwave Corporation:
20 Alpha Road, Chelmsford, MA 01824 Phone: 978-250-3343 Fax: 978-250-3373
Order On-line at www.hittite.com

LP4C (E) – 4 x 4 mm QUAD FLATPACK
NO-LEAD (QFN) PLASTIC PACKAGE

LP4C (E) Package Outline Drawing

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